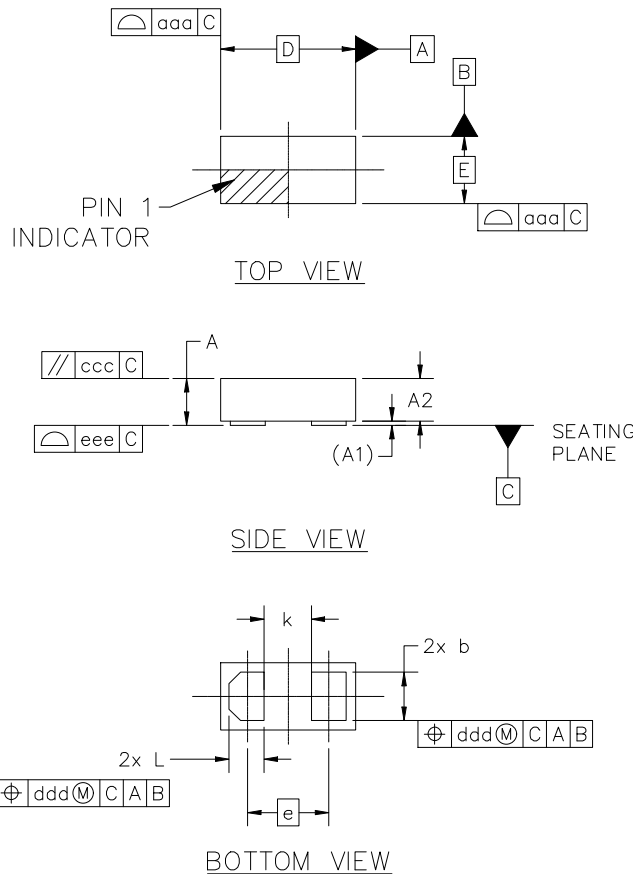


X4DFN2, 0.60x0.30x0.19, 0.36P
CASE 152AX
ISSUE J

DATE 06 FEB 2025

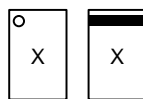


MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.175	0.200	0.225
A1	0.018 REF		
A2	0.180	0.190	0.200
b	0.205	0.215	0.225
D	0.600 BSC		
E	0.300 BSC		
e	0.360 BSC		
k	0.180	---	---
L	0.145	0.155	0.165
TOLERANCE FORM AND POSITION			
aaa	0.025		
ccc	0.020		
ddd	0.050		
eee	0.010		

NOTES:

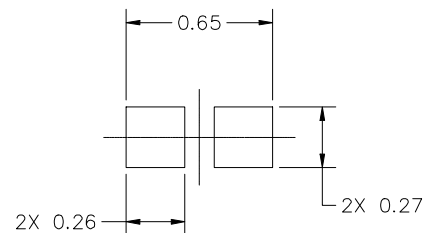
1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.

GENERIC MARKING DIAGRAM*



X = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	X4DFN2, 0.60x0.30x0.19, 0.36P	PAGE 1 OF 1

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